

**DESCRIPTION**

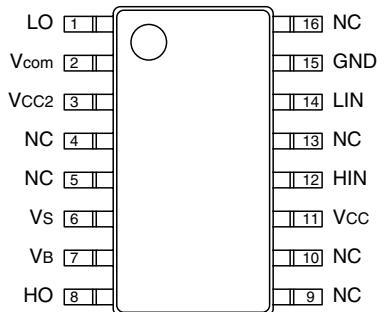
M81723FP is high voltage Power MOSFET and IGBT module driver for half bridge applications.

**FEATURES**

- FLOATING SUPPLY VOLTAGE ..... 600V
- OUTPUT CURRENT ..... +130mA/-100mA (typ)
- UNDERRVOLTAGE LOCKOUT
- SOP-16 PACKAGE

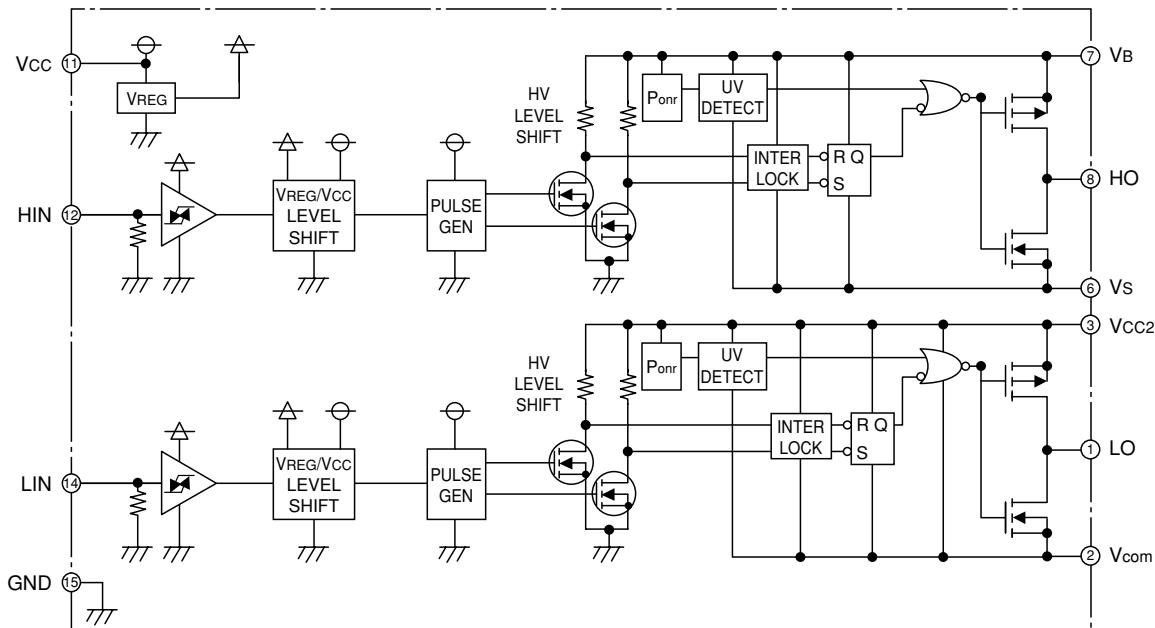
**APPLICATIONS**

IGBT/MOSFET driver

**PIN CONFIGURATION (TOP VIEW)**

NC: NO CONNECTION

Outline:16P2N

**BLOCK DIAGRAM**

## HIGH VOLTAGE HALF BRIDGE DRIVER

## ABSOLUTE MAXIMUM RATINGS (Ta = 25°C unless otherwise specified)

Symbol	Parameter	Test conditions	Ratings	Unit
V <sub>B</sub>	High Side Floating Supply Absolute Voltage		-0.5 ~ 624	V
V <sub>S</sub>	High Side Floating Supply Offset Voltage		V <sub>B</sub> -24 ~ V <sub>B</sub> +0.5	V
V <sub>BS</sub>	High Side Floating Supply Voltage	V <sub>BS</sub> = V <sub>B</sub> -V <sub>S</sub>	-0.5 ~ 24	V
V <sub>HO</sub>	High Side Output Voltage		V <sub>S</sub> -0.5 ~ V <sub>B</sub> +0.5	V
V <sub>CC2</sub>	Low Side Floating Supply Absolute Voltage		-0.5 ~ 624	V
V <sub>com</sub>	Output Standard Voltage		V <sub>CC2</sub> -24 ~ V <sub>CC2</sub> +0.5	V
V <sub>CC2com</sub>	Low Side Floating Supply Voltage	V <sub>CC2com</sub> = V <sub>CC2</sub> -V <sub>com</sub>	-0.5 ~ 24	V
V <sub>LO</sub>	Low Side Output Voltage		V <sub>com</sub> -0.5 ~ V <sub>CC2</sub> +0.5	V
V <sub>CC</sub>	Low Side Fixed Supply Voltage		-0.5 ~ 24	V
V <sub>IN</sub>	Logic Input Voltage	HIN, LIN	-0.5 ~ V <sub>CC</sub> +0.5	V
dV <sub>S</sub> /dt	Allowable Offset Voltage Transient		±50	V/ns
P <sub>d</sub>	Package Power Dissipation	T <sub>a</sub> = 25°C, On Board	0.11	W
K <sub>θ</sub>	Linear Derating Factor	T <sub>a</sub> > 25°C, On Board	-8.9	mW/°C
R <sub>th(j-c)</sub>	Junction-Case Thermal Resistance		45	°C/W
T <sub>j</sub>	Junction Temperature		-40 ~ 125*	°C
T <sub>opr</sub>	Operation Temperature		-40 ~ 100	°C
T <sub>stg</sub>	Storage Temperature		-55 ~ 150	°C
T <sub>L</sub>	Solder Heat-proof (Reflow)	Pb Free	255:10s, max 260	°C

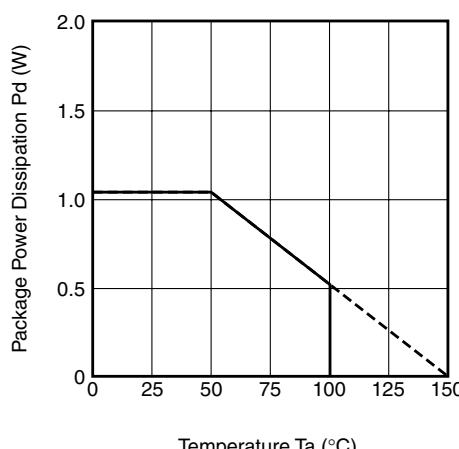
\* Please adjust the V<sub>S</sub> potential to 500V or less when the junction temperature (T<sub>j</sub>) exceeds 125°C.

## RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Typ.	Max.	
V <sub>B</sub>	High Side Floating Supply Absolute Voltage		V <sub>S</sub> +10	—	V <sub>S</sub> +20	V
V <sub>S</sub>	High Side Floating Supply Offset Voltage	V <sub>B</sub> > 10V	-5	—	500	V
V <sub>BS</sub>	High Side Floating Supply Voltage	V <sub>BS</sub> = V <sub>B</sub> -V <sub>S</sub>	10	—	20	V
V <sub>HO</sub>	High Side Output Voltage		V <sub>S</sub>	—	V <sub>B</sub>	V
V <sub>CC2</sub>	Low Side Floating Supply Absolute Voltage		V <sub>com</sub> +10	—	V <sub>com</sub> +20	V
V <sub>com</sub>	Output Standard Voltage	V <sub>CC2</sub> > 10V	-5	—	500	V
V <sub>CC2com</sub>	Low Side Floating Supply Voltage	V <sub>CC2com</sub> = V <sub>CC2</sub> -V <sub>com</sub>	10	—	20	V
V <sub>LO</sub>	Low Side Output Voltage		V <sub>com</sub>	—	V <sub>CC2</sub>	V
V <sub>CC</sub>	Low Side Fixed Supply Voltage		10	—	20	V
V <sub>IN</sub>	Logic Input Voltage	HIN, LIN	0	—	V <sub>CC</sub>	V

\* For proper operation, the device should be used within the recommended conditions.

## THERMAL DERATING FACTOR CHARACTERISTIC (MAXIMUM RATING)



Aug. 2009

## HIGH VOLTAGE HALF BRIDGE DRIVER

**ELECTRICAL CHARACTERISTICS (Ta = 25°C, VCC = VCC2com (= Vcc2-Vcom) = VBS (= VB-Vs) = 15V, Vs = Vcom = 0V, unless otherwise specified)**

Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Typ.*	Max.	
I <sub>FS</sub>	Floating Supply Leakage Current	V <sub>B</sub> = V <sub>S</sub> = 600V	—	—	1.0	µA
I <sub>Fcom</sub>	V <sub>com</sub> Floating Supply Leakage Current	V <sub>CC2</sub> = V <sub>com</sub> = 600V	—	—	1.0	µA
I <sub>BS</sub>	V <sub>BS</sub> Standby Current	HIN = LIN = 0V	—	0.20	0.4	mA
I <sub>CC</sub>	V <sub>CC</sub> Standby Current	HIN = LIN = 0V	—	0.30	0.6	mA
I <sub>CC2</sub>	V <sub>CC2</sub> Standby Current	HIN = LIN = 0V	—	0.20	0.4	mA
I <sub>BSH</sub>	V <sub>BS</sub> Standby Current H	HIN = 5V	—	0.25	0.5	mA
I <sub>CCH</sub>	V <sub>CC</sub> Standby Current H	HIN = 5V	—	0.37	0.75	mA
I <sub>CC2H</sub>	V <sub>CC2</sub> Standby Current H	HIN = 5V	—	0.20	0.4	mA
I <sub>BSL</sub>	V <sub>BS</sub> Standby Current L	LIN = 5V	—	0.20	0.4	mA
I <sub>CLL</sub>	V <sub>CC</sub> Standby Current L	LIN = 5V	—	0.37	0.75	mA
I <sub>CC2L</sub>	V <sub>CC2</sub> Standby Current L	LIN = 5V	—	0.25	0.5	mA
V <sub>OH</sub>	High Level Output Voltage	I <sub>O</sub> = 0A, LO, HO	14.9	—	—	V
V <sub>OL</sub>	Low Level Output Voltage	I <sub>O</sub> = 0A, LO, HO	—	—	0.1	V
V <sub>IH</sub>	High Level Input Threshold Voltage	HIN, LIN	4.0	—	—	V
V <sub>IL</sub>	Low Level Input Threshold Voltage	HIN, LIN	—	—	0.6	V
V <sub>INh</sub>	Input Hysteresis Voltage	V <sub>INh</sub> = V <sub>IH</sub> -V <sub>IL</sub>	1.0	1.5	2.0	V
I <sub>IIH5</sub>	High Level Input Bias Current 5	V <sub>IN</sub> = 5V	—	25	75	µA
I <sub>IIH15</sub>	High Level Input Bias Current 15	V <sub>IN</sub> = 15V	—	75	150	µA
I <sub>IL</sub>	Low Level Input Bias Current	V <sub>IN</sub> = 0V	—	—	1.0	µA
V <sub>BSSuvr</sub>	V <sub>BS</sub> Supply UV Reset Voltage		7.2	8.4	9.7	V
V <sub>BSSuvh</sub>	V <sub>BS</sub> Supply UV Hysteresis Voltage		0.1	0.4	0.7	V
t <sub>VBSuv</sub>	V <sub>BS</sub> Supply UV Filter Time		—	7.5	—	µs
V <sub>CC2uvr</sub>	V <sub>CC2</sub> Supply UV Reset Voltage		7.2	8.4	9.7	V
V <sub>CC2uvh</sub>	V <sub>CC2</sub> Supply UV Hysteresis Voltage		0.1	0.4	0.7	V
t <sub>VCC2ur</sub>	V <sub>CC2</sub> Supply UV Filter Time		—	7.5	—	µs
V <sub>Ponr</sub>	Power-On Reset Voltage		—	—	6.0	V
t <sub>Ponr(FIL)</sub>	Power-On Reset Filter Time		300	—	—	ns
I <sub>OH</sub>	Output High Level Short Circuit Pulsed Current	V <sub>O</sub> = 0V, V <sub>IN</sub> = 5V, PW < 10µs	80	130	180	mA
I <sub>OL</sub>	Output Low Level Short Circuit Pulsed Current	V <sub>O</sub> = 15V, V <sub>IN</sub> = 0V, PW < 10µs	60	100	140	mA
R <sub>OH</sub>	Output High Level On Resistance	I <sub>O</sub> = -20mA, R <sub>OH</sub> = (V <sub>OH</sub> -V <sub>O</sub> )/I <sub>O</sub>	—	55	100	Ω
R <sub>OL</sub>	Output Low Level On Resistance	I <sub>O</sub> = 20mA, R <sub>OL</sub> = V <sub>O</sub> /I <sub>O</sub>	—	45	70	Ω
t <sub>dLH(HO)</sub>	High Side Turn-On Propagation Delay	CL = 200pF between HO-V <sub>S</sub>	75	95	120	ns
t <sub>dHL(HO)</sub>	High Side Turn-Off Propagation Delay	CL = 200pF between HO-V <sub>S</sub>	85	115	145	ns
t <sub>rH</sub>	High Side Turn-On Rise Time	CL = 200pF between HO-V <sub>S</sub>	15	35	70	ns
t <sub>fH</sub>	High Side Turn-Off Fall Time	CL = 200pF between HO-V <sub>S</sub>	10	30	80	ns
t <sub>dLH(LO)</sub>	Low Side Turn-On Propagation Delay	CL = 200pF between LO-V <sub>com</sub>	70	95	120	ns
t <sub>dHL(LO)</sub>	Low Side Turn-Off Propagation Delay	CL = 200pF between LO-V <sub>com</sub>	85	115	145	ns
t <sub>rL</sub>	Low Side Turn-On Rise Time	CL = 200pF between LO-V <sub>com</sub>	15	35	70	ns
t <sub>fL</sub>	Low Side Turn-Off Fall Time	CL = 200pF between LO-V <sub>com</sub>	10	30	80	ns
Δt <sub>dLH</sub>	Delay Matching, High Side and Low Side Turn-On	t <sub>dLH(HO)</sub> -t <sub>dLH(LO)</sub>	—	—	15	ns
Δt <sub>dHL</sub>	Delay Matching, High Side and Low Side Turn-Off	t <sub>dHL(HO)</sub> -t <sub>dHL(LO)</sub>	—	—	15	ns
V <sub>OPW</sub>	Output Pulse Width	V <sub>IN</sub> : PW = 200ns	200	220	240	ns

\* Typ. is not specified.

**HIGH VOLTAGE HALF BRIDGE DRIVER****FUNCTION TABLE**

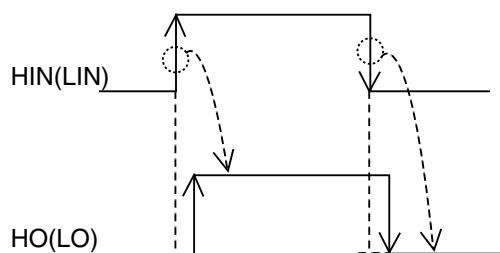
HIN	LIN	VBS UV	VCC2com UV	HO	LO	Behavioral state
H→L	H→L	H	H	L	L	LO = HO = Low
H→L	L→H	H	H	L	H	LO = High
L→H	H→L	H	H	H	L	HO = High
L→H	L→H	H	H	H	H	LO = HO = High
X	H→L	L	H	L	L	HO = Low, VBS UV tripped
X	L→H	L	H	L	H	LO = High, VBS UV tripped
H→L	X	H	L	L	L	LO = Low, VCC2com UV tripped
L→H	X	H	L	H	L	HO = High, VCC2com UV tripped

Note1 : "L" state of Vbs UV, Vcc UV means that UV trip voltage.

2 : In the case of both input signals (HIN and LIN) are "H", output signals (HO and LO) become "H".

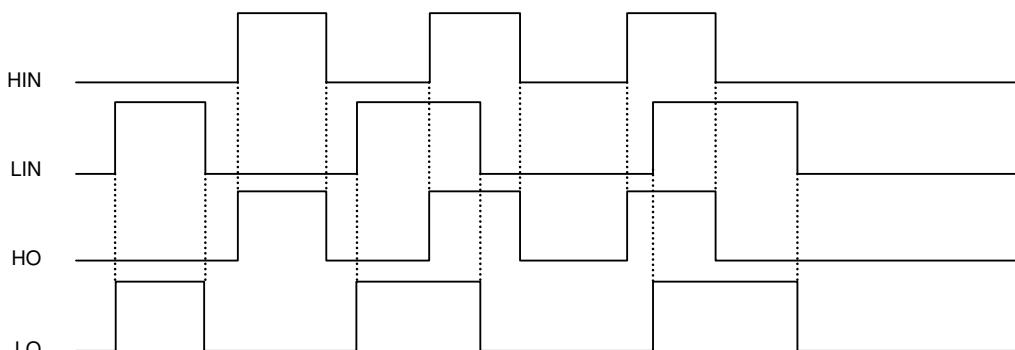
3 : X : L→H or H→L.

4 : Output signal (HO, LO) is triggered by the edge of input signal.

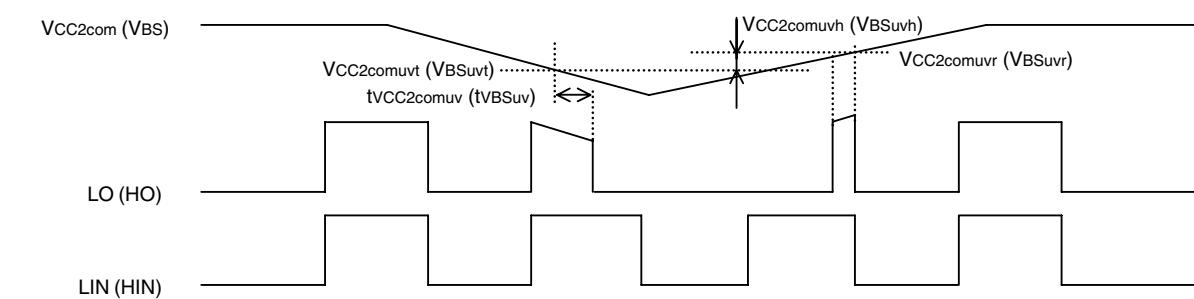
**TIMING DIAGRAM****1. Input/Output Timing Diagram**

HIGH ACTIVE (When input signal (HIN or LIN) is "H", then output signal (HO or LO) is "H".)

In the case of both input signals (HIN and LIN) are "H", output signals (HO and LO) become "H".

**2. Vcc2com (VBS) Supply Under Voltage Lockout Timing Diagram**

If supply voltage drops below UV trip voltage( $V_{CC2comuv} = V_{BSUvt} - V_{BSUvh}$ ) for supply UV filter time, output signal becomes "L". As soon as supply voltage is higher than UV reset voltage, output becomes normal.



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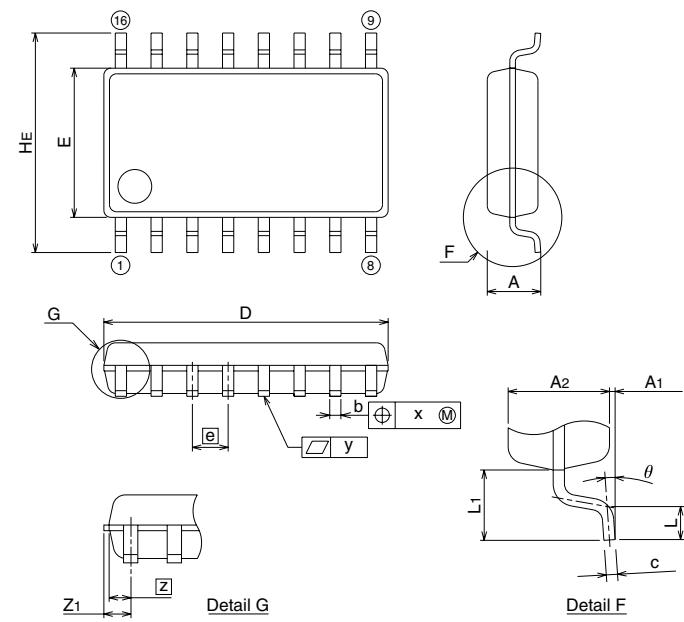
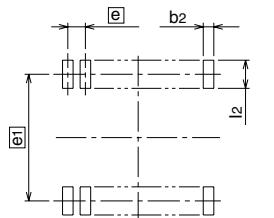
**HIGH VOLTAGE HALF BRIDGE DRIVER****3. Allowable Supply Voltage Transient**

It is recommended to supply Vcc firstly and supply VCC2com secondly and supply VBS at last. In the case of shutting off supply voltage, please shut off VBS supply voltage firstly. Secondly, shut off VCC2com Supply Voltage. And at last, shutting off Vcc supply voltage.

When applying VCC2com and VBS, power supply should be applied slowly. If it rises rapidly, output signal (HO or LO) may be malfunction.

**PACKAGE OUTLINE****16P2N-A (MMP)**

EIAJ Package Code	JEDEC Code	Weight(g)	Lead Material
SOP16-P-300-1.27	P	0.2	Cu Alloy

**Plastic 16pin 300mil SOP**

Symbol	Dimension in Millimeters		
	Min	Nom	Max
A	—	—	2.1
A <sub>1</sub>	0	0.1	0.2
A <sub>2</sub>	P	1.8	P
b	0.35	0.4	0.5
c	0.18	0.2	0.25
D	10.0	10.1	10.2
E	5.2	5.3	5.4
[e]	P	1.27	P
HE	7.5	7.8	8.1
L	0.4	0.6	0.8
L <sub>1</sub>	P	1.25	P
[Z]	P	0.605	P
Z <sub>1</sub>	P	P	0.755
x	P	P	0.25
y	P	P	0.1
θ	0°	P	8°
b <sub>2</sub>	P	0.76	P
[e <sub>1</sub> ]	P	7.62	P
l <sub>2</sub>	1.27	P	P